LOW-PROFILE DUAL WIPE SOCKET

**Mates with:**
FTSH, FTS, FW

---

**APPLICATIONS**

- CLP
- FTSH
- HORIZONTAL
- PASS-THRU

---

**SPECIFICATIONS**

For complete specifications and recommended PCB layouts see www.samtec.com?CLP

- **Insulator Material:** Black Liquid Crystal Polymer
- **Contact Material:** Phosphor Bronze
- **Plating:**
  - Sn or Au over 50 μ" (1.27 μm) Ni
  - Current Rating (CLP/FTSH): 3.4 A per pin (2 pins powered)
- **Voltage Rating:** 280 VAC/395 VDC
- **Operating Temp Range:** -55 °C to +125 °C
- **Insertion Depth:**
  - Top Entry = (1.40 mm) .055" minimum, Bottom Entry = (2.41 mm) .095" minimum plus board thickness DH Entry = (2.31 mm) .091" to (2.67 mm) .105"
- **Normal Force:** 60 grams (0.59 N) average
- **Max Cycles:** 100 with 10 µ" (0.25 µm) Au
- **RoHS Compliant:** Yes

---

**PROCESSING**

- **Lead-Free Solderable:** Yes
- **SMT Lead Coplanarity:**
  - (0.10 mm) .004" max (02-35)
  - (0.15 mm) .006" max (36-50)
  - (.004" stencil solution may be available; contact IPG@samtec.com)

---

**RECOGNITIONS**

For complete scope of recognitions see www.samtec.com/quality

---

**ALSO AVAILABLE (MOQ Required)**

- Single row
- Other platings
  - Contact Samtec.
- **Note:** Some sizes, styles and options are non-standard, non-returnable.

---

**OTHER OPTION**

- **–BE** = Bottom Entry (Required for bottom entry applications)
- **–A** = Alignment Pin (Not available with –PA option)
- **–K** = (4.00 mm) .157" DIA Polyimide film Pick & Place Pad (5 positions min.)
- **–P** = Pick & Place Pad (5 positions min. –D only)
  - (Not always necessary for auto placement. See Flex Processing.)
- **–PA** = Pick & Place Pad with Alignment Pin
  - (Not Available with –A option)
- **–TR** = Tape & Reel

---

**FILE NO. E111594**

**F-218 (Rev 14DEC17)**

---

**Due to technical progress, all designs, specifications and components are subject to change without notice.**

---

**WWW.SAMTEC.COM**

Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.